

XN04402 (XN4402)

Silicon PNP epitaxial planar type

For general amplification

■ Features

- Two elements incorporated into one package
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- 2SB0710 (2SB710) \times 2

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

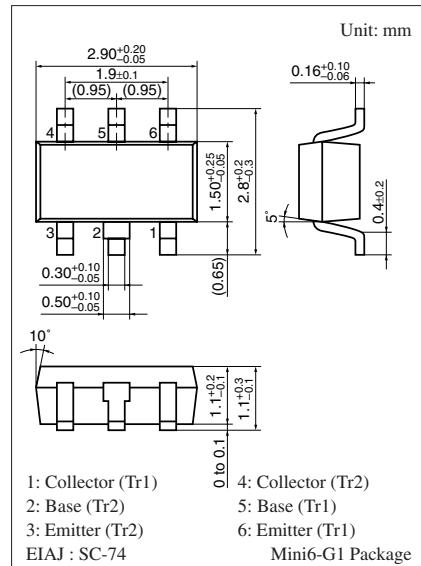
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-60	V
Collector-emitter voltage (Base open)	V_{CEO}	-50	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_C	-500	mA
Peak collector current	I_{CP}	-1	A
Total power dissipation	P_T	300	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10 \mu\text{A}, I_E = 0$	-60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20 \text{ V}, I_E = 0$			-0.1	μA
Forward current transfer ratio *	h_{FE1}	$V_{CE} = -10 \text{ V}, I_C = -150 \text{ mA}$	85		340	—
	h_{FE2}	$V_{CE} = -10 \text{ V}, I_C = -500 \text{ mA}$	40			—
Collector-emitter saturation voltage *	$V_{CE(\text{sat})}$	$I_C = -300 \text{ mA}, I_B = -30 \text{ mA}$		-0.35	-0.60	V
Base-emitter saturation voltage *	$V_{BE(\text{sat})}$	$I_C = -300 \text{ mA}, I_B = -30 \text{ mA}$		-1.1	-1.5	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$	200			MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$	6	15		pF

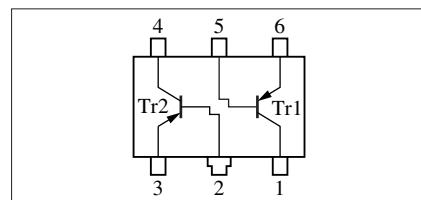
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Pulse measurement



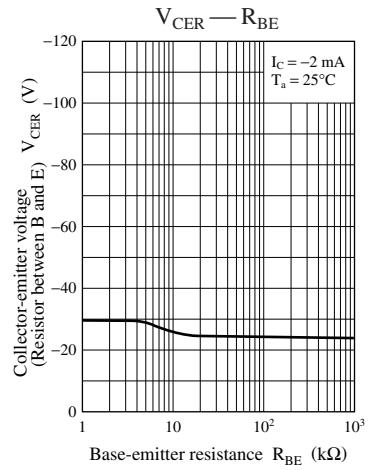
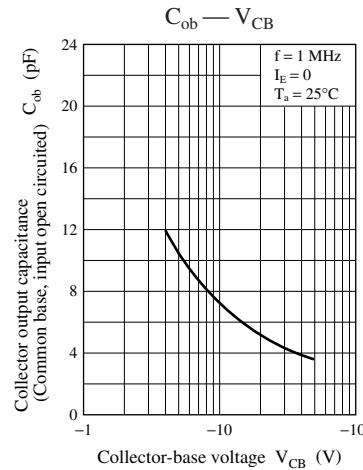
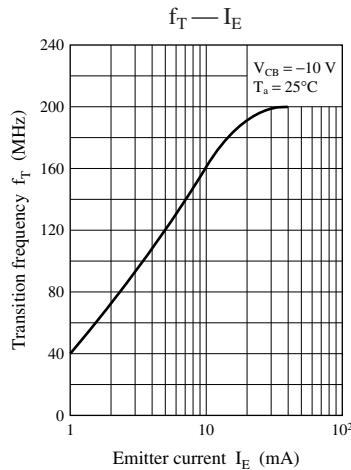
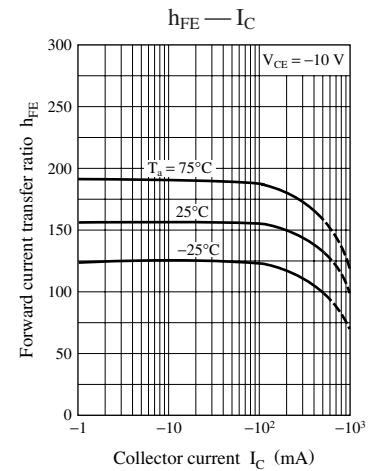
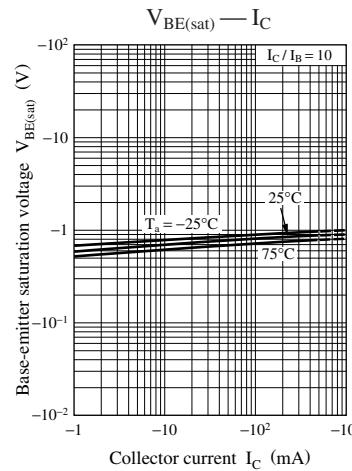
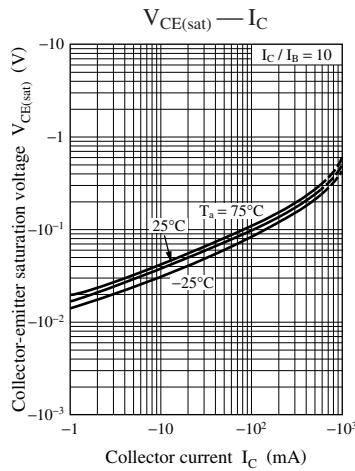
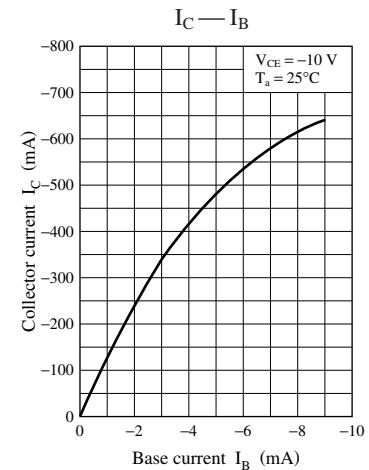
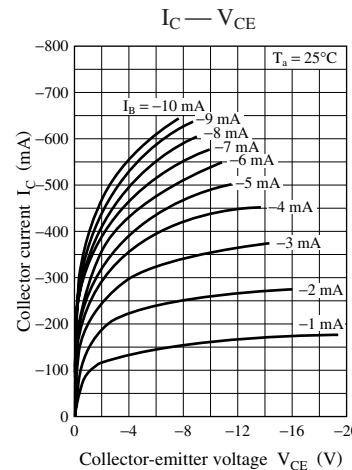
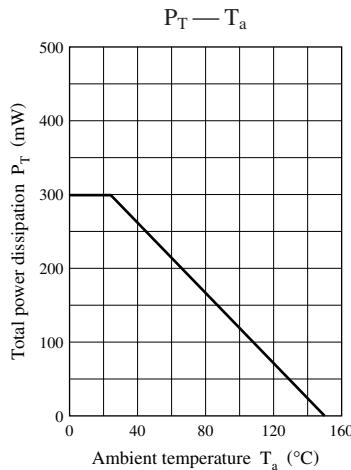
Marking Symbol: OH

Internal Connection



Note) The part number in the parenthesis shows conventional part number.

XN04402



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